



Product Change Notification / JAON-18YCSW720

Date:

05-May-2023

Product Category:

Broadband Gateway

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5014.003 and 6256 Final Notice: Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9653AQC, LE9653AQCT, LE9643AQC, and LE9643AQCT catalog part numbers (CPN) available in 36L VQFN (4x6x1mm) package assembled at ASEM assembly site.

Affected CPNs:

[JAON-18YCSW720_Affected_CPN_05052023.pdf](#)

[JAON-18YCSW720_Affected_CPN_05052023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9653AQC, LE9653AQCT, LE9643AQC, and LE9643AQCT catalog part numbers (CPN) available in 36L VQFN (4x6x1mm) package assembled at ASEM assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
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Fabrication Location	Die # 1	Global Foundries, Singapore - Fab 7 (GF07)		Global Foundries, Singapore - Fab 7 (GF07)	
	Die # 2	Global Foundries, Singapore - Fab 2 (GF02)	Microchip Technology Colorado – Fab 5 (MCSO)	Global Foundries, Singapore - Fab 2 (GF02)	Microchip Technology Colorado – Fab 5 (MCSO)
Die Size	Die # 1	2.204 x 2.258 mm		1.932x1.860mm	
		Please see attached pre and post change comparison for Die # 1 Location			
	Die # 2	1.57 x 1.72 mm		1.57 x 1.72 mm	
Assembly Site		ASE Group -Malaysia (ASEM)		ASE Group -Malaysia (ASEM)	
Wire Material		CuPdAu		CuPdAu	
Die Attach Material		CRM1076DS		CRM1076DS	
Molding Compound Material		CEL-9240HF10AK-G1		CEL-9240HF10AK-G1	
Lead Frame Material		C194FH		C194FH	

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying a new die size.

Change Implementation Status:In Progress

Estimated First Ship Date:May 06, 2023 (date code: 2318)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	May 2022				>	May 2023				
Workweek	19	20	21	22		18	19	20	21	22
Initial PCN Issue Date				x						
Qual Report Availability						x				

Final PCN Issue Date						X				
Estimated Implementation Date						X				

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:May 24, 2022: Issued initial notification.

May 05, 2023: Issued final notification. Attached the Qualification Report. Updated the affected CPN list. Provided estimated first ship date to be on May 06, 2023.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-18YCSW720_Pre and Post Change_Summary.pdf](#)

[PCN_JAON-18YCSW720_Qual Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

LE9653AQC

LE9653AQCT

LE9643AQC

LE9643AQCT